

Title (en)

METHOD AND DEVICE FOR COATING SUBSTRATES BY MEANS OF BIPOLAR PULSE MAGNETRON SPUTTERING AND THE USE THEREOF

Title (de)

VERFAHREN UND EINRICHTUNG ZUM BESCHICHTEN VON SUBSTRATEN MITTELS BIPOLARER PULS-MAGNETRON-ZERSTÄUBUNG UND DEREN ANWENDUNG

Title (fr)

PROCEDE ET DISPOSITIF PERMETTANT DE RECOUVRIR DES SUBSTRATS PAR PULVERISATION MAGNETRON A IMPULSIONS BIPOLAIRES ET LEUR UTILISATION

Publication

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Application

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Abstract (en)

[origin: DE19860474A1] The invention relates to a method and device for coating substrates by means of bipolar pulse magnetron sputtering using three or more targets. The substrates are placed opposite the targets essentially in the range of a high plasma density, whereby at least two targets are connected to a potential-free bipolar power supply device and are sputtered for a predetermined period of time. The selection of the target respectively connected to the bipolar power supply device is altered during the course of the coating process according to a technologically predetermined program. The device is comprised of at least three magnetron sources (17, 17', 17'') provided with targets (18, 18', 18''), of a potential-free bipolar power supply device (21), and of a switching device (20) for switching the current electrical connection of selected targets with the bipolar power supply device (21) according to a technologically predetermined program.

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